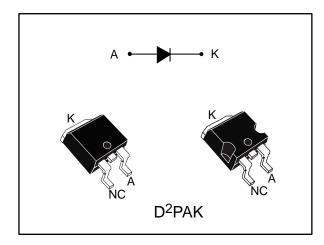
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STTH10R04

High efficiency rectifier

Datasheet - production data



Features

- Ultrafast recovery
- Low power losses
- High surge capability
- Low leakage current
- High junction temperature
- ECOPACK[®]2 compliant component for D²PAK on demand

Description

The device is an ultrafast recovery power rectifier dedicated to energy recovery in PDP application.

It is especially designed for clamping function in energy recovery block.

The compromise between forward voltage drop and recovery time offers optimized performance.

Table 1: Device summary

Symbol	Value
I _{F(peak)}	10 A
V _{RRM}	400 V
T _j (max)	175 °C
V _F (typ)	1.15 V
t _{rr} (typ.)	15 ns

Characteristics STTH10R04

1 Characteristics

Table 2: Absolute ratings (limiting values, at 25 °C, unless otherwise specified)

Symbol	Parameter	Value	Unit	
V _{RRM}	Repetitive peak reverse voltage	400	V	
I _{F(RMS)}	Forward rms current	20	Α	
I _{F(peak)}	Peak working forward current $ T_{C} = 135 ^{\circ}C $		10	Α
I _{FSM}	Surge non repetitive forward current tp = 10 ms sinusoidal		100	Α
T _{stg}	Storage temperature range	-65 to +175	°C	
Tj	Maximum operating junction temperature	175	°C	

Table 3: Thermal parameter

Symbol	Parameter	Max. value	Unit
R _{th(j-c)}	Junction to case	3.5	°C/W

Table 4: Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
L (1)	1 (1)		M M	-		10	
IR''	I _R ⁽¹⁾ Reverse leakage current	T _j = 125 °C	$V_R = V_{RRM}$	-	10	100	μA
V _F (2)	Forward voltage drap	T _j = 25 °C	I 10 A	-	1.50	1.70	V
VF(=)	V _F ⁽²⁾ Forward voltage drop	T _j = 125 °C	$I_F = 10 \text{ A}$	-	1.15	1.35	V

Notes:

 $^{(1)}$ Pulse test: t_p = 5 ms, δ < 2%

 $^{(2)} Pulse$ test: t_p = 380 $\mu s, \, \delta < 2\%$

To evaluate the conduction losses, use the following equation:

 $P = 1.05 \text{ x } I_{F(AV)} + 0.03 \text{ x } I_{F^2(RMS)}$

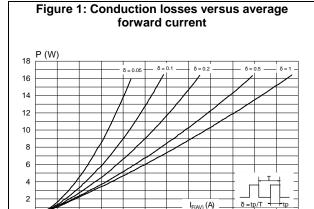
STTH10R04 Characteristics

Table 5: Dynamic electrical characteristics

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
	Reverse recovery	T. 25 °C	$I_F = 0.5 A,$ $I_{rr} = 0.25 A,$ $I_R = 1 A$	-	15	20	9
Lrr	t_{rr} time $T_j = 25 \text{ °C}$	1j = 25 °C	I _F = 1 A, V _R = 30 V, dI _F /dt = -50 A/µs	-		40	ns
t _{fr}	Forward recovery time	T _j = 25 °C	I _F = 10 A, dI _F /dt = 100 A/μs V _{FR} = 1.1 x V _{Fmax}	-		140	ns
V _{FP}	Forward recovery voltage	T _j = 25 °C	I _F = 10 A, dI _F /dt = 100 A/μs	-		3	V
I _{RM}	Reverse recovery current	T _j = 125 °C	I _F = 10 A, V _R = 200 V	-	6.2	8.0	Α
Sfactor	Softness factor		dI _F /dt = 200 A/μs	-	0.3		-

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1.1 Characteristics (curves)



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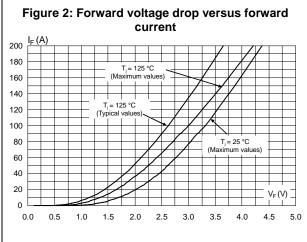
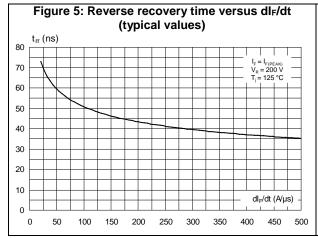
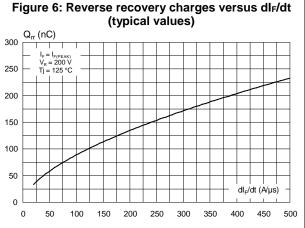


Figure 3: Relative variation of thermal impedance junction to case versus pulse duration $Z_{th(j-c)}/R_{th(j-c)}$ 1.0 0.9 0.8 0.7 0.6 0.5 0.4 0.3 0.2 0.1 tp(s) 0.0 шш 1.E-04 1.E-03 1.E-02 1.E-01 1.E+00

Figure 4: Peak reverse recovery current versus dl_F/dt (typical values) I_{RM} (A) 14 13 I_F = I_{F(PEAK)} V_R = 200 V T_i = 125 °C 12 11 10 9 8 7 6 5 4 3 2 1 dl_F/dt (A/µs) 0 0 50 300 400





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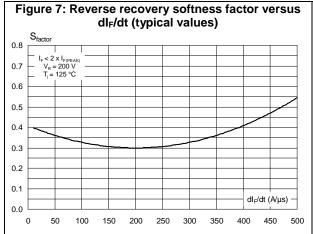
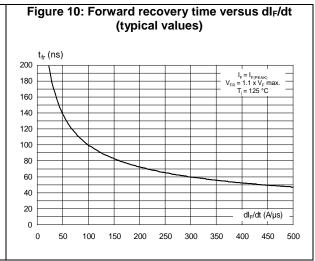
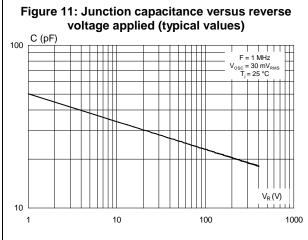
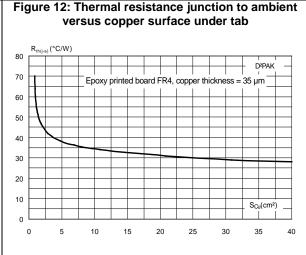


Figure 8: Relative variation of dynamic parameters versus junction temperature 3.0 $\begin{array}{c} I_{F} = I_{F(PEAK)} \\ V_{R} = 200 \text{ V} \\ \end{array}$ Reference: $T_{j} = 125 \text{ °C}$ 2.8 2.6 2.4 2.2 2.0 1.8 1.6 1.4 1.2 1.0 0.8 0.6 0.4 T_j (°C) 0.2 0.0 75 25 50 100 125

Figure 9: Forward recovery voltage versus dlr/dt (typical values) $V_{FP}(V)$ 12 I_F = I_{F(PEAK)} T_: = 125 °C 11 10 9 8 6 5 4 3 2 1 dl_F/dt (A/µs) 0 0 200 300 350 50 100 150 250 400 450







Package information STTH10R04

2 Package information

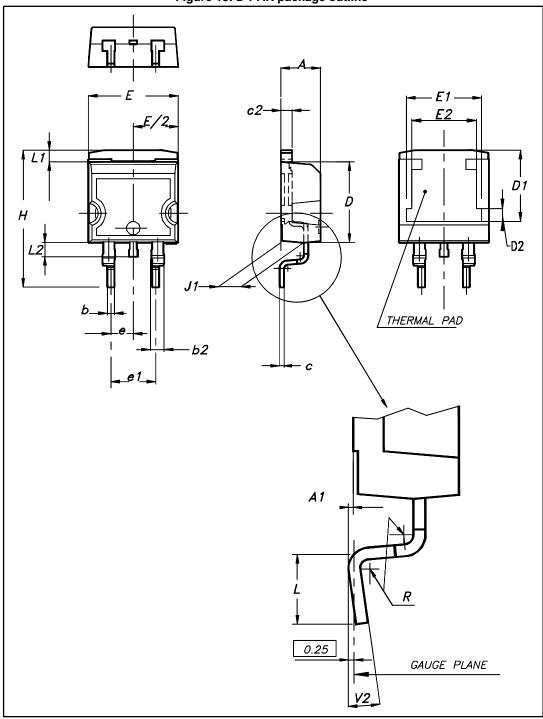
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

- Cooling method: by conduction (C)
- Epoxy meets UL94,V0

STTH10R04 Package information

2.1 D²PAK package information

Figure 13: D²PAK package outline





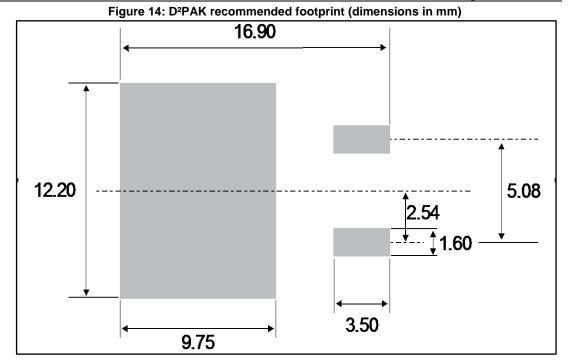
This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

Table 6: D²PAK package mechanical data

	Dimensions				
Ref.	Millim		Inches		
	Min.	Max.	Min.	Max.	
А	4.36	4.60	0.172	0.181	
A1	0.00	0.25	0.000	0.010	
b	0.70	0.93	0.028	0.037	
b2	1.14	1.70	0.045	0.067	
С	0.38	0.69	0.015	0.027	
c2	1.19	1.36	0.047	0.053	
D	8.60	9.35	0.339	0.368	
D1	6.90	8.00	0.272	0.311	
D2	1.10	1.50	0.043	0.060	
Е	10.00	10.55	0.394	0.415	
E1	8.10	8.90	0.319	0.346	
E2	6.85	7.25	0.266	0.282	
е	2.54	typ.	0.1	00	
e1	4.88	5.28	0.190	0.205	
Н	15.00	15.85	0.591	0.624	
J1	2.49	2.90	0.097	0.112	
L	1.90	2.79	0.075	0.110	
L1	1.27	1.65	0.049	0.065	
L2	1.30	1.78	0.050	0.070	
R	0.4	typ.	0.0)15	
V2	0°	8°	0°	8°	

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STTH10R04 Package information





Ordering information STTH10R04

3 Ordering information

Table 7: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STTH10R04G-TR	STTH10R04G	D ² PAK	1.38 g	1000	Tape and reel

4 Revision history

Table 8: Document revision history

Date	Revision	Changes
07-Nov-2007	1 First issue.	
08-Aug-2017	2	Updated features and package silhouette. Minor text changes to improve readability. Updated Section 1: "Characteristics", Section 1.1: "Characteristics (curves)", Section 2: "Package information" and Section 3: "Ordering information".

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